



SHENZHEN LONG JING MICRO-ELECTRONICS CO., LTD.

# TO-220 Plastic-Encapsulate Thyristors

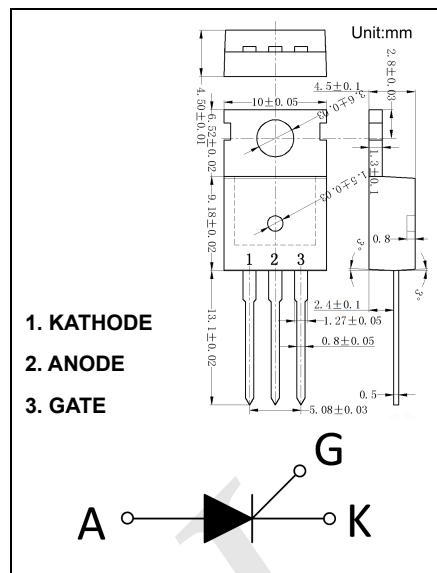
**ALJCT616**

10A Silicon Controlled Rectifier

**Description**

ALJCT616 series of silicon controlled rectifiers, with high ability to withstand the shock loading of large current, provide high dv/dt rate with strong resistance to electromagnetic interference. They are especially recommended for use on solid state relay, motorcycle, power charger, T-tools etc.

ALJCT616A provides insulation voltage rated at 2500V RMS and ALJCT616F provides insulation voltage rated at 2000V RMS from all three terminals to external heatsink.

**Maximum Ratings ( $T_j=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Value	Unit
$I_{T(\text{RMS})}$	RMS on-state current	16	A
$I_{\text{TSM}}$	Non repetitive surge peak on-state current( $t_p=10\text{ms}$ )	190	A
$V_{\text{DRM}}$	Repetitive peak off-state voltage	500	V
$V_{\text{RRM}}$	Repetitive peak reverse voltage	500	V
$V_{\text{DSM}}$	Non repetitive surge peak Off-state voltage	$V_{\text{DRM}} + 100$	V
$V_{\text{RSM}}$	Non repetitive peak reverse voltage	$V_{\text{RRM}} + 100$	V
$I^2t$	$I^2t$ value for fusing ( $t_p=10\text{ms}$ )	180	$\text{A}^2\text{s}$
$dI/dt$	Critical rate of rise of on-state current( $I_G = 2 \times I_{GT}$ )	50	$\text{A}/\mu\text{s}$
$I_{GM}$	Peak gate current	4	A
$P_{G(\text{AV})}$	Average gate power dissipation	1	W
$P_{GM}$	Peak gate power	5	W
$T_j$	Junction Temperature	-40 ~ 125	$^\circ\text{C}$
$T_{\text{stg}}$	Storage Temperature	-40 ~ 150	$^\circ\text{C}$

**Thermal Resistances**

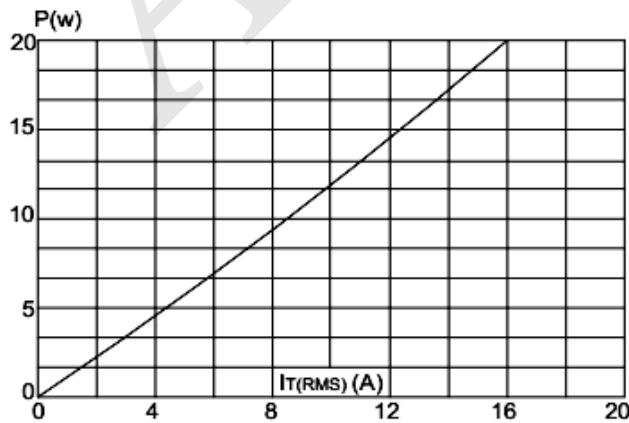
Symbol	Parameter	Value	Unit
$R_{\theta JC}$	junction to case	2.3	$^\circ\text{C}/\text{W}$

## Electrical Characteristics ( $T_j=25^\circ\text{C}$ unless otherwise specified)

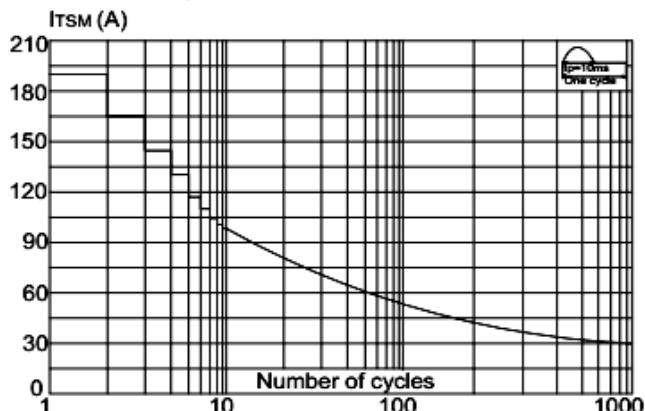
Symbol	Test Conditions	Min	Typ	Max	Unit
$I_{GT}$	$V_D = 12\text{V}$ , $R_L = 33\Omega$			15	mA
$V_{GT}$				1.3	V
$V_{GD}$	$V_D = V_{DRM}$ , $T_j = 125^\circ\text{C}$ , $R_L = 3.3\text{K}\Omega$	0.2			V
$I_L$	$I_G = 1.2I_{GT}$			60	mA
$I_H$	$I_T = 500\text{mA}$			40	mA
$dV/dt$	$V_D = 2/3V_{DRM}$ , Gate Open $T_j = 125^\circ\text{C}$	500			V/ $\mu\text{s}$
$V_{TM}$	$I_{TM} = 32\text{A}$ , $t_p = 380\mu\text{s}$			1.6	V
$I_{DRM}$	$V_D = V_{DRM}$	$T_j = 25^\circ\text{C}$		5	$\mu\text{A}$
$I_{RRM}$	$V_R = V_{RRM}$			2	mA

## Typical Characteristics

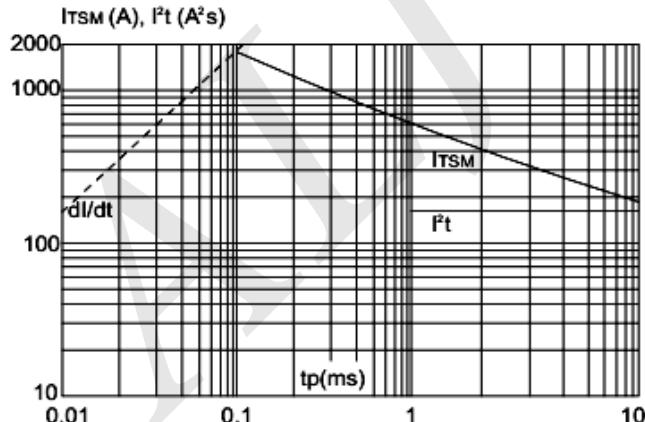
**FIG.1** Maximum power dissipation versus RMS on-state current



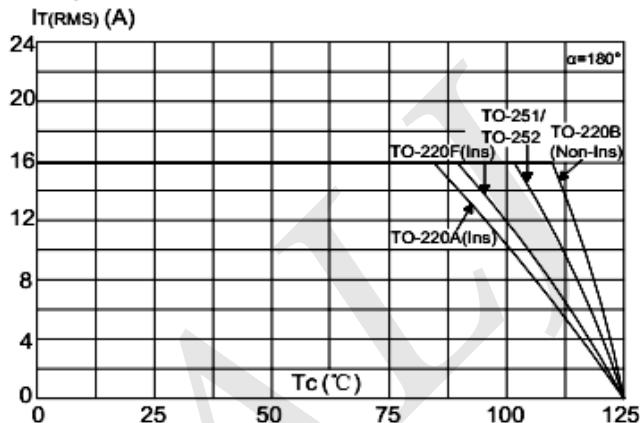
**FIG.3:** Surge peak on-state current versus number of cycles



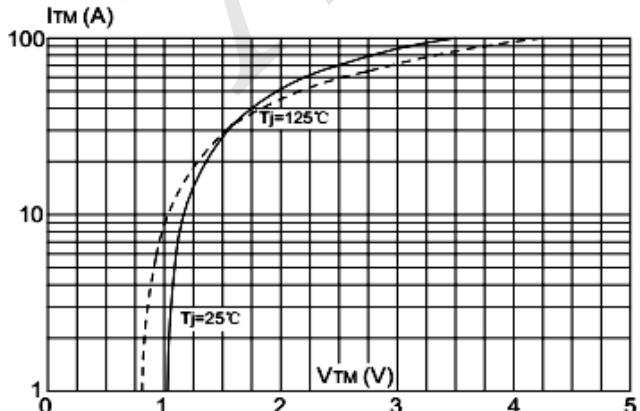
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 10\text{ms}$ , and corresponding value of  $I^t$  ( $dI/dt < 50\text{A}/\mu\text{s}$ )



**FIG.2:** RMS on-state current versus case temperature



**FIG.4:** On-state characteristics (maximum values)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature

